DRV3245E-Q1 3-Phase Grade 0 Automotive Gate Driver Unit (GDU) With High Performance Sensing, Protection and Diagnostics

1 Features

- AEC-Q100 qualified for automotive applications:
  - Device temperature grade 0: –40°C to +150°C, T_A
- SafeTI™semiconductor component
  - Developed according to the applicable requirements of ISO 26262
- 4.5-V to 45-V operating voltage
- Programmable peak gate drive currents up to 1A
- Charge-pump gate driver for 100% Duty Cycle
- Current-shunt amplifiers and phase comparators
  - A Device: 3 current-shunt amplifiers and 3-phase comparators with status through SPI
  - B Device: 2 current-shunt amplifiers and 3-phase comparators with real-time monitor through digital pins
- 3-PWM or 6-PWM input control up to 20 kHz
- Single PWM-mode commutation capability
- Supports both 3.3-V and 5-V digital interface
- Serial peripheral interface (SPI)
- Thermally-enhanced 48-Pin HTQFP
- Protection features:
  - Internal regulators, battery voltage monitor
  - SPI CRC
  - Clock monitor
  - Analog built-in self test
  - Programmable dead-time control
  - MOSFET shoot-through prevention
  - MOSFET V_{DS} overcurrent monitors
  - Gate-source voltage real time monitor
  - Overtemperature warning

2 Applications

- High temperature 12-V automotive applications
  - Automated manual transmission and dual clutch transmission
  - Shift by wire
  - Transfer case and pumps

3 Description

The DRV3245E-Q1 device is a FET gate driver IC for three-phase motor-drive applications. The device is intended for high-temperature automotive applications and is designed according to the applicable requirements of ISO 26262 for functional safety applications. The device provides three half-bridge drivers each capable of driving a high-side and low-side N-channel MOSFET while also providing sophisticated protection and monitoring of the FETs. A charge-pump driver enables 100% duty cycle and supports low battery voltages during cold-crank operation. The integration of current-sense amplifiers, integrated phase comparators, and SPI-based configuration enable reduction of the bill of materials (BOM) and space on the printed circuit board (PCB) because of the elimination of most external and passive components.

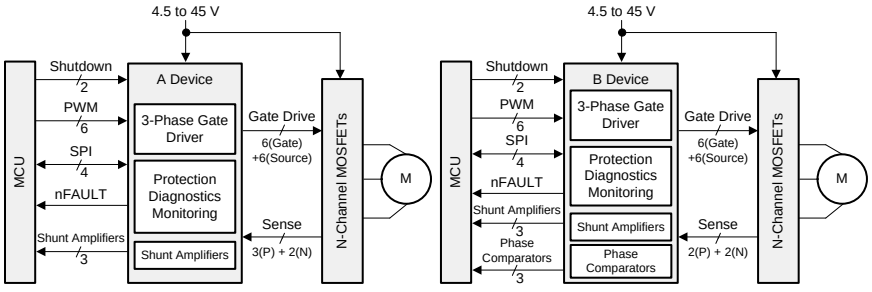
The DRV3245E-Q1 device also integrates diagnostics and protection for each internal block and provides support for common system diagnostic checks each of which can be instantiated and reported through SPI. This flexibility of the integrated features allows the device to integrate seamlessly into a variety of safety architectures.

Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
DRV3245E-Q1	HTQFP (48)	7.00 mm × 7.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

4 Device and Documentation Support

4.1 Device Support

4.1.1 Device Nomenclature

Figure 1 shows a legend for reading the complete orderable device name for the DRV3245E-Q1 device

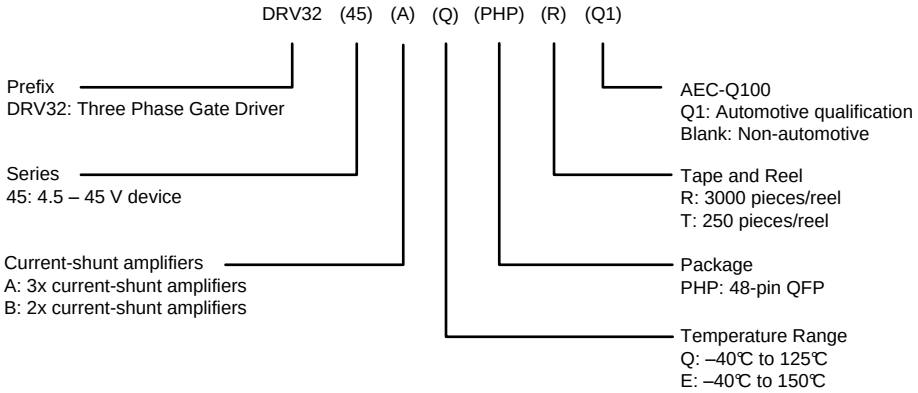


Figure 1. Device Nomenclature

4.2 Documentation Support

For related documentation see the following:

- Texas Instruments, *PowerPAD™ Thermally Enhanced Package* application report
- Texas Instruments, *PowerPAD™ Made Easy* application report
- Texas Instruments, *Sensored 3-Phase BLDC Motor Control Using MSP430* application report
- Texas Instruments, *Understanding IDRIVE and TDRIVE in TI Motor Gate Drivers* application report

4.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

4.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

4.5 Trademarks

SafeTI, E2E are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.

4.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

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4.7 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DRV3245AEPHPRQ1	ACTIVE	HTQFP	PHP	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 150	D3245AE	Samples
DRV3245BEPHPRQ1	ACTIVE	HTQFP	PHP	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 150	D3245BE	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

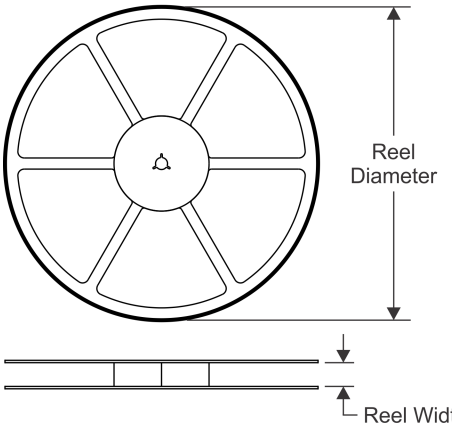
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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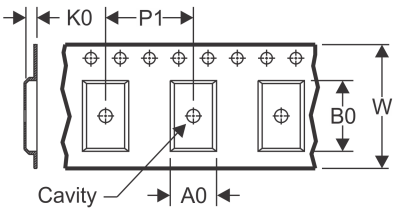
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

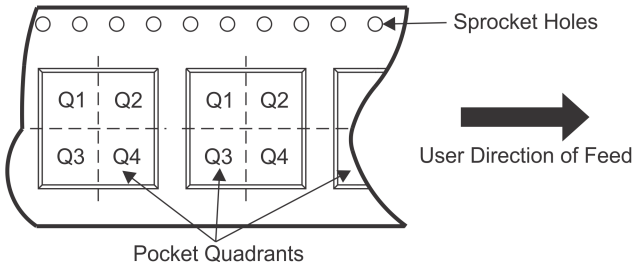


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

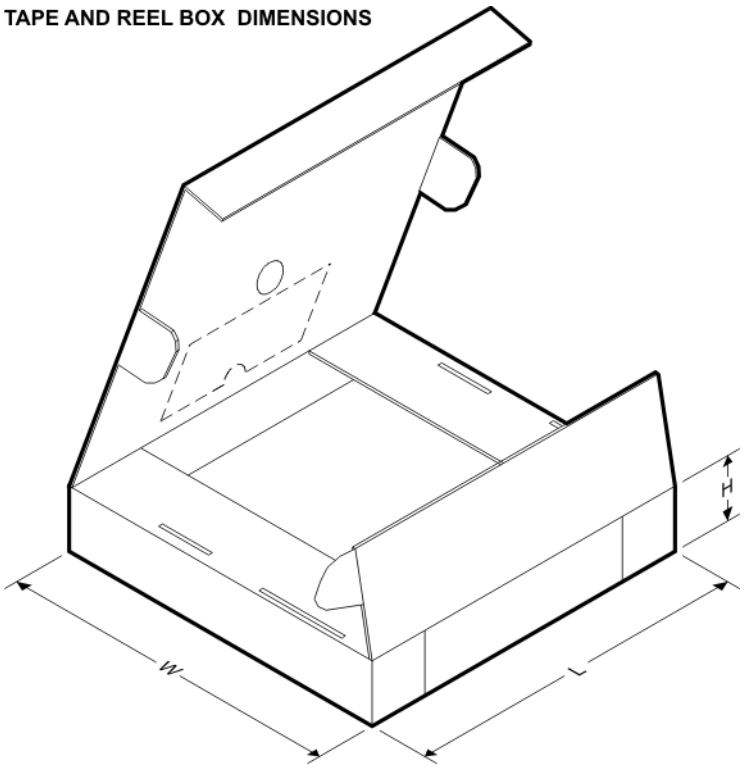
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV3245AEPHPRQ1	HTQFP	PHP	48	1000	330.0	16.4	9.6	9.6	1.5	12.0	16.0	Q2
DRV3245BEPHPRQ1	HTQFP	PHP	48	1000	330.0	16.4	9.6	9.6	1.5	12.0	16.0	Q2

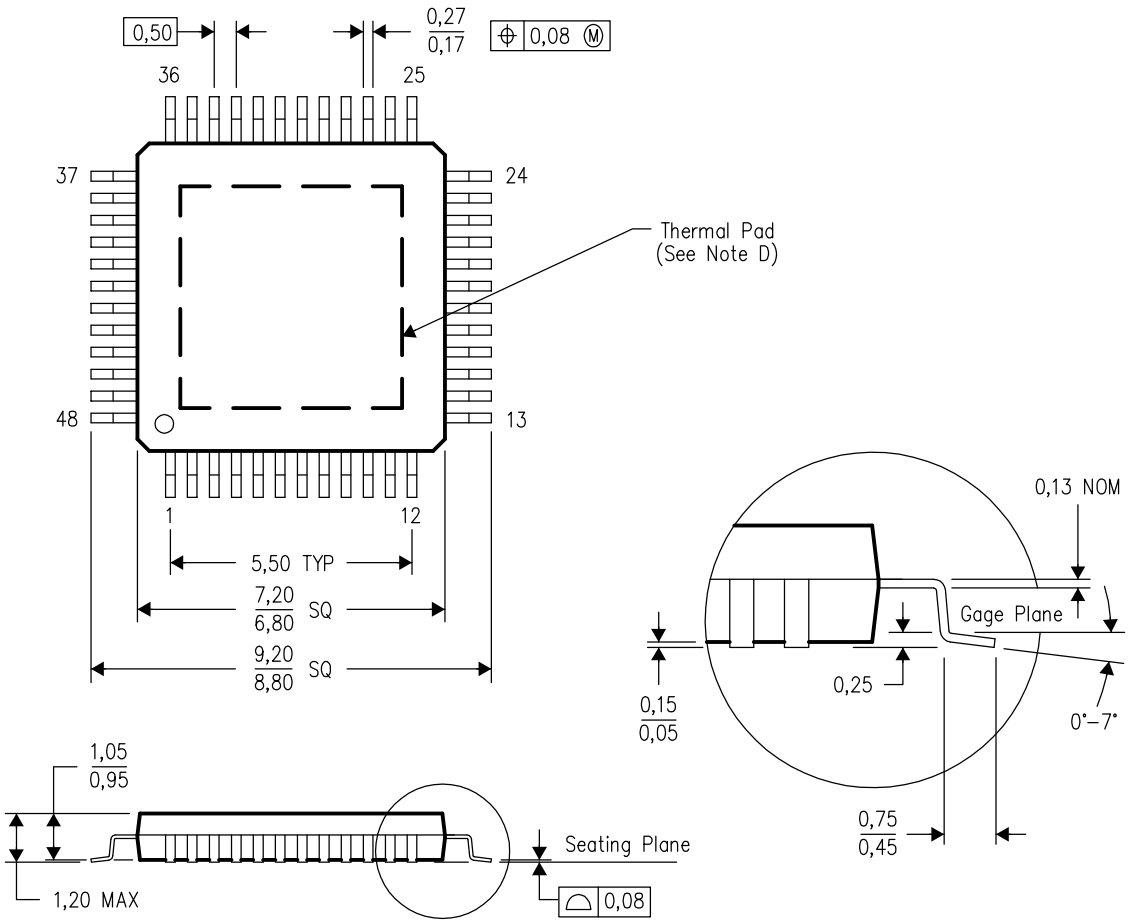
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV3245AEPHPRQ1	HTQFP	PHP	48	1000	350.0	350.0	43.0
DRV3245BEPHPRQ1	HTQFP	PHP	48	1000	350.0	350.0	43.0

PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MS–026

PowerPAD is a trademark of Texas Instruments.

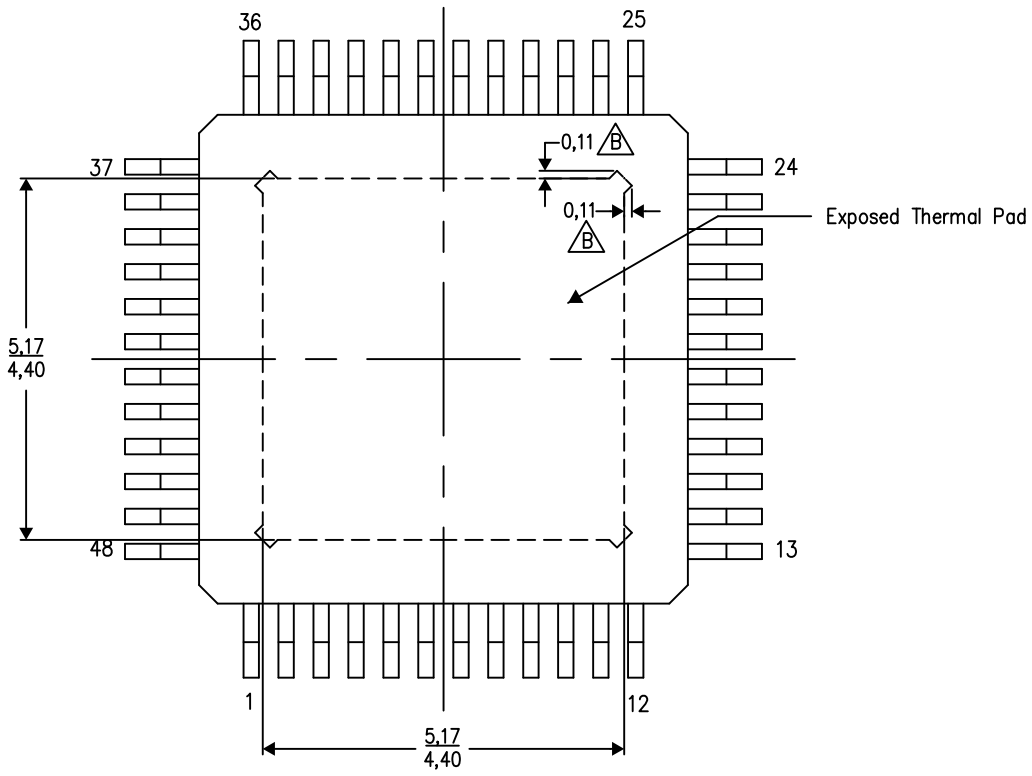
PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

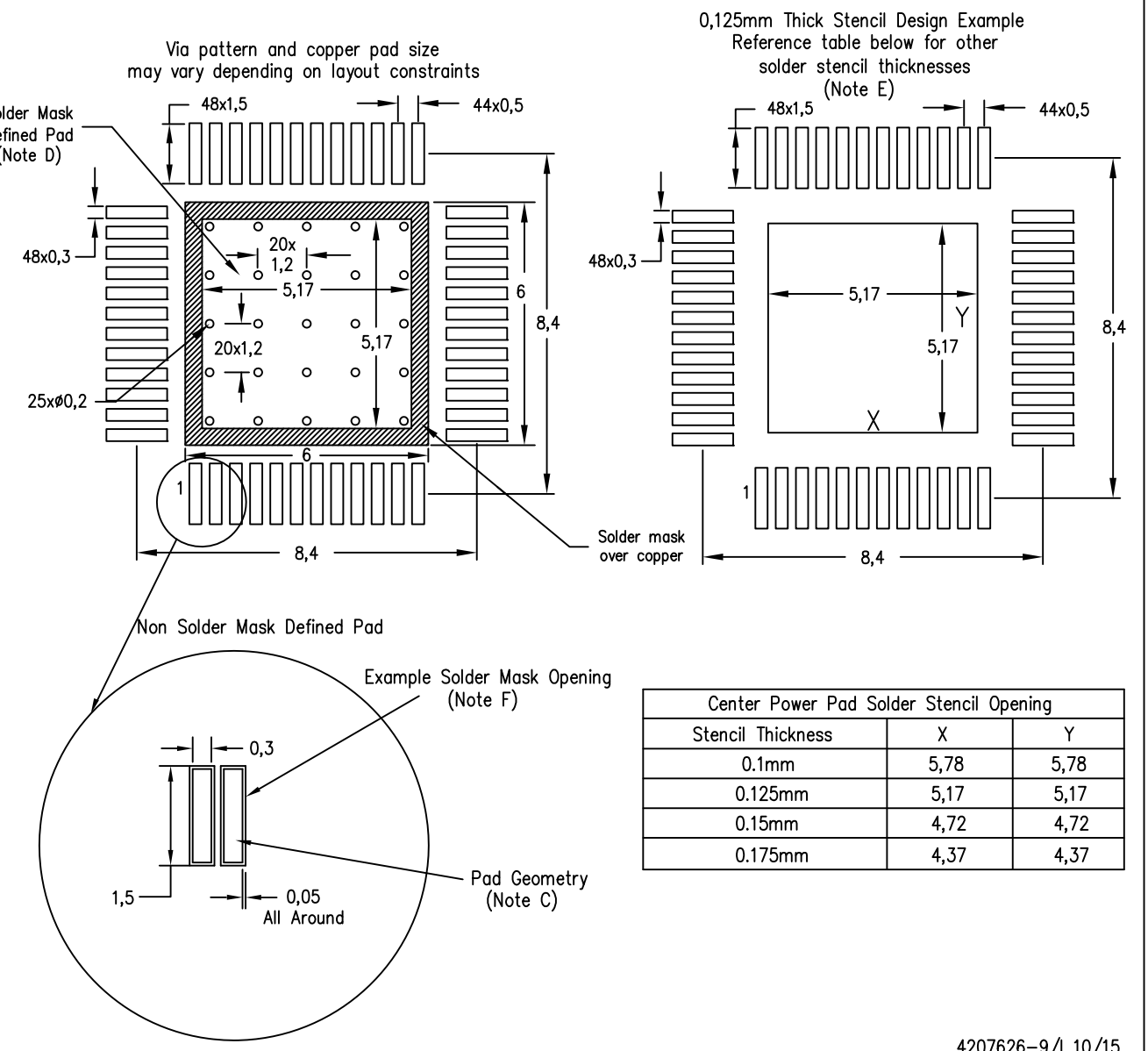
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NOTE: A. All linear dimensions are in millimeters

B Tie strap features may not be present.

PowerPAD is a trademark of Texas Instruments

PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



Center Power Pad Solder Stencil Opening		
Stencil Thickness	X	Y
0.1mm	5,78	5,78
0.125mm	5,17	5,17
0.15mm	4,72	4,72
0.175mm	4,37	4,37

4207626–9/I 10/15

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting options for vias placed in the thermal pad.

PowerPAD is a trademark of Texas Instruments

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